QPTECHNOLOGIES

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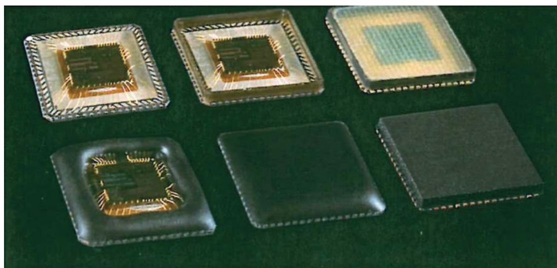
Encapsulation Options

Advantages:

- Choose the encapsulation style that meets your prototyping needs
- Mix and match multiple encapsulation options on the same assembly order
- Assembly turn times from 8 hours to 3 days available



Flattened/Remolded (fully encapsulated with filled epoxy using QP Technologies' proprietary molding process)

- Test socket compatible/meets JEDEC mechanical standards
- Suitable for customer samples, preproduction runs, etc.
- Auto-handling compliant
- Electrical performance equivalent to production package
- Optional marking/branding service available

Glob Top (fully encapsulated with filled epoxy – domed-top surface)

- Electrical performance equivalent to production package
- Optional marking/branding service available
- Suitable for chip-on-board applications

Partial Open Cavity (encapsulated with filled epoxy in selected areas)

- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Wires partially protected from mechanical damage

Open Cavity with Frame or Lid (no encapsulant, custom frame and/or lid)

- Die and wires protected, yet accessible
- Ease of probing die and chip
- Test socket compatible
- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Suitable for MEMS applications

Open Cavity (wire-bonded chip with no encapsulant, die is exposed)

- Ease of probing die and chip
- FIB ready, UV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.

Clear Encapsulant (encapsulated with nonfilled epoxy)

- Easy wire-bonding verification
- Visual sample of assembled product
- Eliminates need for X-ray wire-length measurements
- Lower dielectric constant
- Suitable for IR or visual light transmission applications

Verisys Registrars®

ISO 9001:2015 Certified
ISO 13485:2016 Certified

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